

Abstract of the Disclosure

5 A photocurable adhesive composition is disclosed which includes a photocurable adhesive and an effective amount of a ceramic-containing modifier which does not substantially reduce a photocure rate of the photocurable adhesive. The modifier alters the flow properties of the composition to facilitate controlled dispensing of the uncured adhesive composition. The modifier alters the thermal expansion properties of the cured composition to reduce bondline stress. The preferred modifier includes inert, alkali alumino-silicate microspheres. A method of adhesive bonding is also disclosed in which an adherend is adhered to a substrate using a photocurable adhesive composition containing a photocurable adhesive and microspheres.